

LUXBEAM® LLS06

6 μm , at 720 wafers an hour

Where fineline PCB and advanced packaging meet: 6 μm line and space from a 405 / 375 nm laser or a 4-peak LED, at the highest throughput in the fine end of the lineup.

Full specification

IMAGING & LAYOUT	
Resolution	6 μm
Light source	405 / 375 nm laser, or 4-peak LED
Throughput — Ø300 mm wafer	720 wph
Throughput — 515 × 510 mm panel	240 pph
Typical applications	Selective AP, IC substrate / glass build-up, mSAP SLP, HBM RDL
Substrate / panel	310×310, 510×515, 600×600
Segment	AP / fine-line PCB

Figures are for discussion and to be confirmed per application. Throughput depends on resist and energy density — send us both and a field application engineer will verify them for your process.